

2SJ350 Silicon P Channel MOS FET

REJ03G0859-0200 (Previous: ADE-208-138) Rev.2.00 Sep 07, 2005

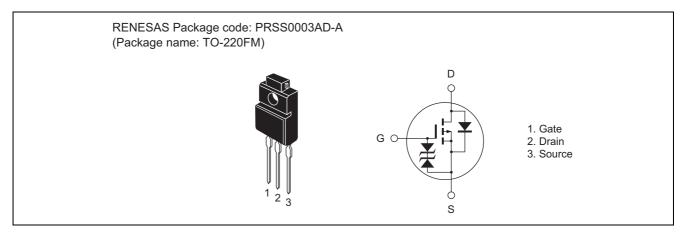
Description

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- 4 V gate drive device can be driven from 5 V source
- Suitable for switching regulator, DC-DC converter

Outline





Absolute Maximum Ratings

(Ta =	25°C)
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ltem	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-120	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	ID	-6	A
Drain peak current	I _{D (pulse)} Note 1	-12	A
Body to drain diode reverse drain current	I _{DR}	-6	A
Channel dissipation	Pch Note 2	20	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

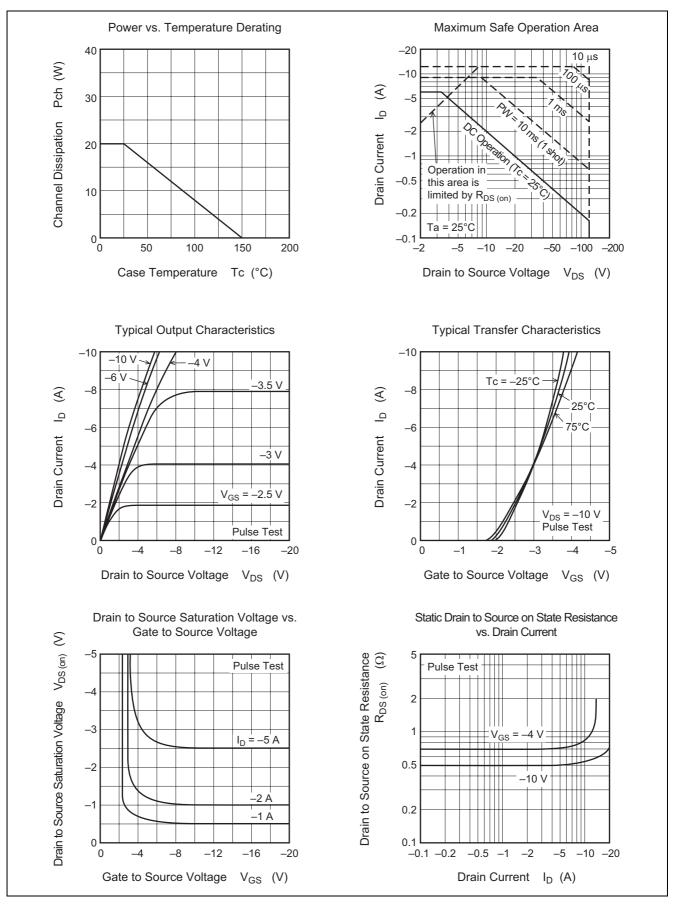
2. Value at Tc = $25^{\circ}C$

Electrical Characteristics

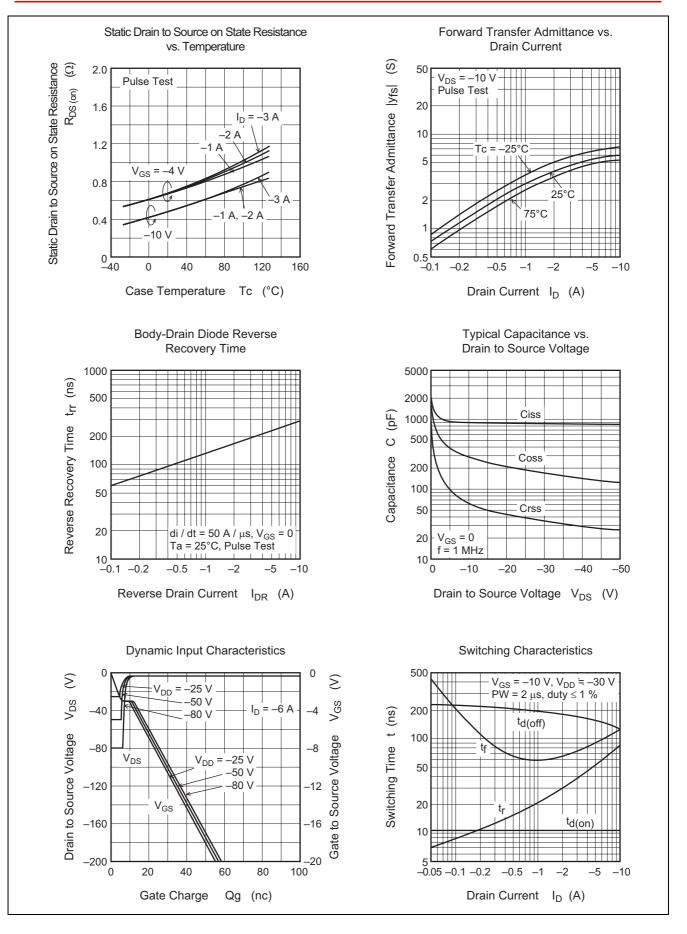
						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	-120	—	—	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V (BR) GSS	±20	—	—	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	—	—	±10	μΑ	$V_{GS} = \pm 16 V, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	—	—	-250	μΑ	$V_{DS} = -100 \text{ V}, \text{ V}_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0	—	-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	—	0.5	0.7	Ω	$I_D = -4 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 3}}$
	R _{DS (on)}	—	0.7	0.9	Ω	$I_D = -4 A, V_{GS} = -4 V^{Note 3}$
Forward transfer admittance	y _{fs}	3.0	5.0	—	S	$I_D = -4 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	—	900	—	pF	$V_{DS} = -10 V$
Output capacitance	Coss	—	265	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	—	65	—	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	—	11	—	ns	$I_D = -4 A$
Rise time	t _r	—	45	—	ns	$V_{GS} = -10 \text{ V}$
Turn-off delay time	t _{d (off)}	—	170	—	ns	$R_L = 7.5 \Omega$
Fall time	t _f	—	80	—	ns	
Body to drain diode forward voltage	V _{DF}	_	-1.2	_	V	$I_F = -6 A, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}		240	_	ns	$I_F = -6 A, V_{GS} = 0$
						di _F /dt = 50 A/µs

Note: 3. Pulse test

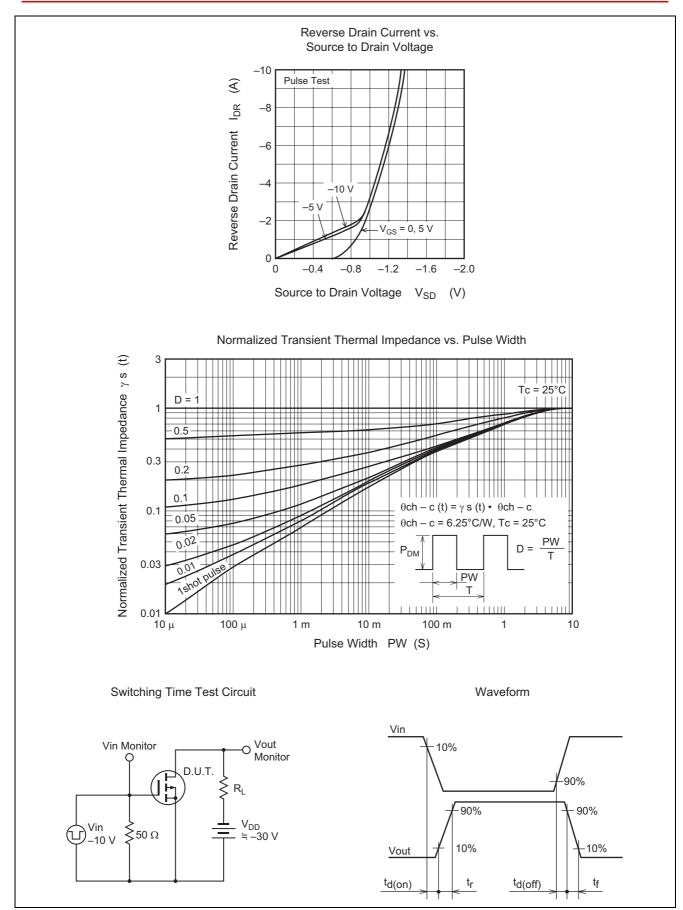
Main Characteristics





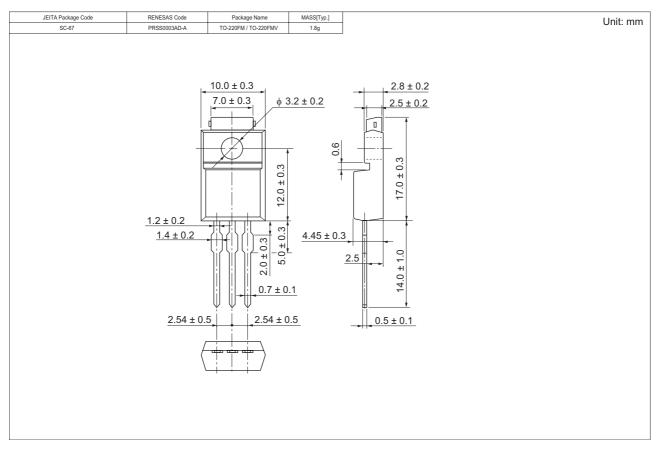


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Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SJ350-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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